

SOT190-1

plastic very small outline package; 56 leads

8 February 2016

Package information

1. Package summary

Terminal position code	D (double)
Package type descriptive code	VSO56
Package type industry code	VSO56
Package style descriptive code	VSO (very thin small outline)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	19-2-2003

Table 1. Package summary

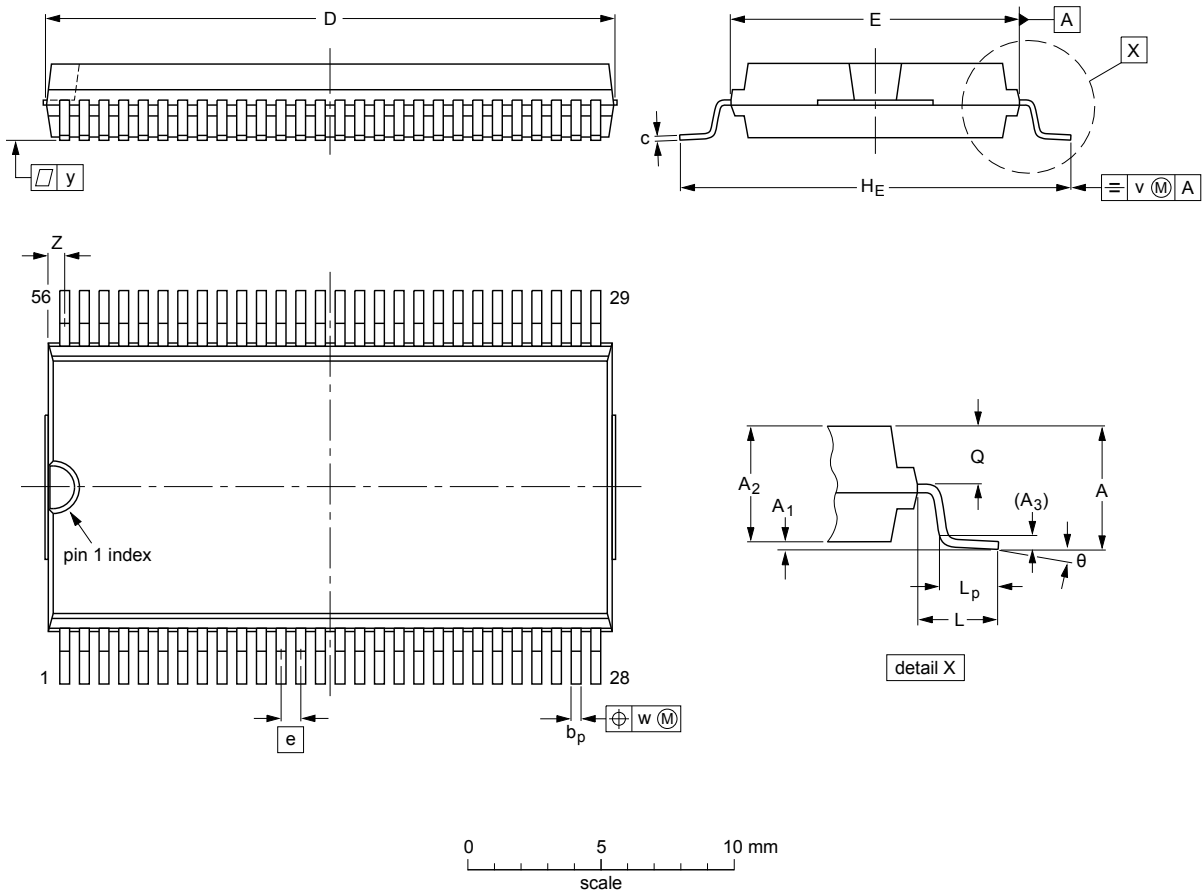
Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	21.35	-	21.5	21.65	mm
E	package width	11	-	11	11.1	mm
A	seated height	[tbd]	-	3.3	3.3	mm
A ₂	package height	2.8	-	2.85	3	mm
n ₂	actual quantity of termination	-	-	56	-	



2. Package outline

VSO56: plastic very small outline package; 56 leads

SOT190-1



DIMENSIONS (inch dimensions are derived from the original mm dimensions)

UNIT	A max.	A ₁	A ₂	A ₃	b _p	c	D ⁽¹⁾	E ⁽²⁾	e	H _E	L	L _p	Q	v	w	y	Z ⁽¹⁾	θ
mm	3.3	0.3 0.1	3.0 2.8	0.25	0.42 0.30	0.22 0.14	21.65 21.35	11.1 11.0	0.75	15.8 15.2	2.25	1.6 1.4	1.45 1.30	0.2	0.1	0.1	0.90 0.55	7° 0°
inches	0.13	0.012 0.004	0.12 0.11	0.01	0.017 0.012	0.0087 0.0055	0.85 0.84	0.44 0.43	0.0295	0.62 0.60	0.089	0.063 0.055	0.057 0.051	0.008	0.004	0.004	0.035 0.022	

Notes

1. Plastic or metal protrusions of 0.3 mm (0.012 inch) maximum per side are not included.
2. Plastic interlead protrusions of 0.25 mm (0.01 inch) maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT190-1						97-08-11 03-02-19

Fig. 1. Package outline VSO56 (SOT190-1)

3. Soldering

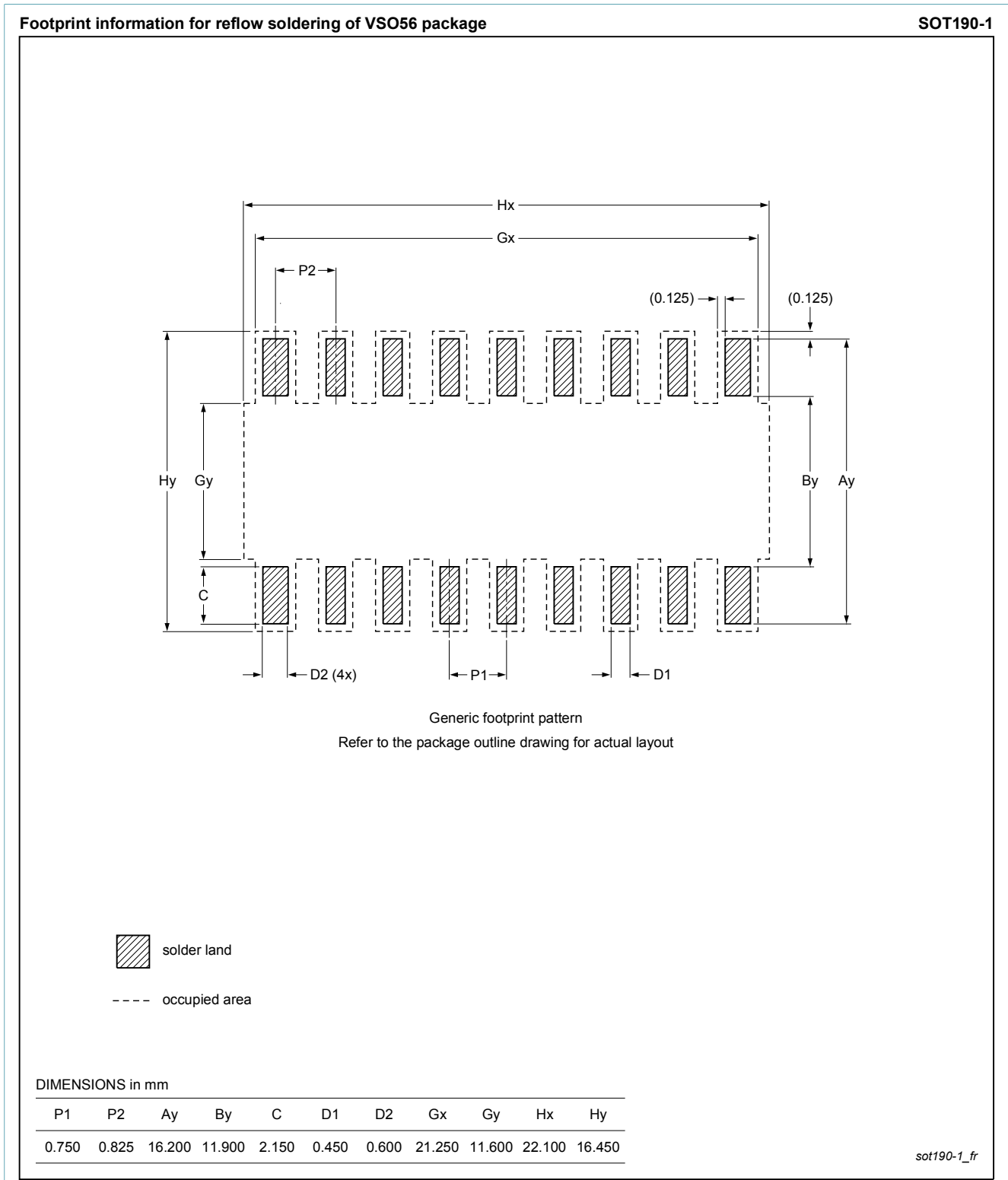


Fig. 2. Reflow soldering footprint for VSO56 (SOT190-1)

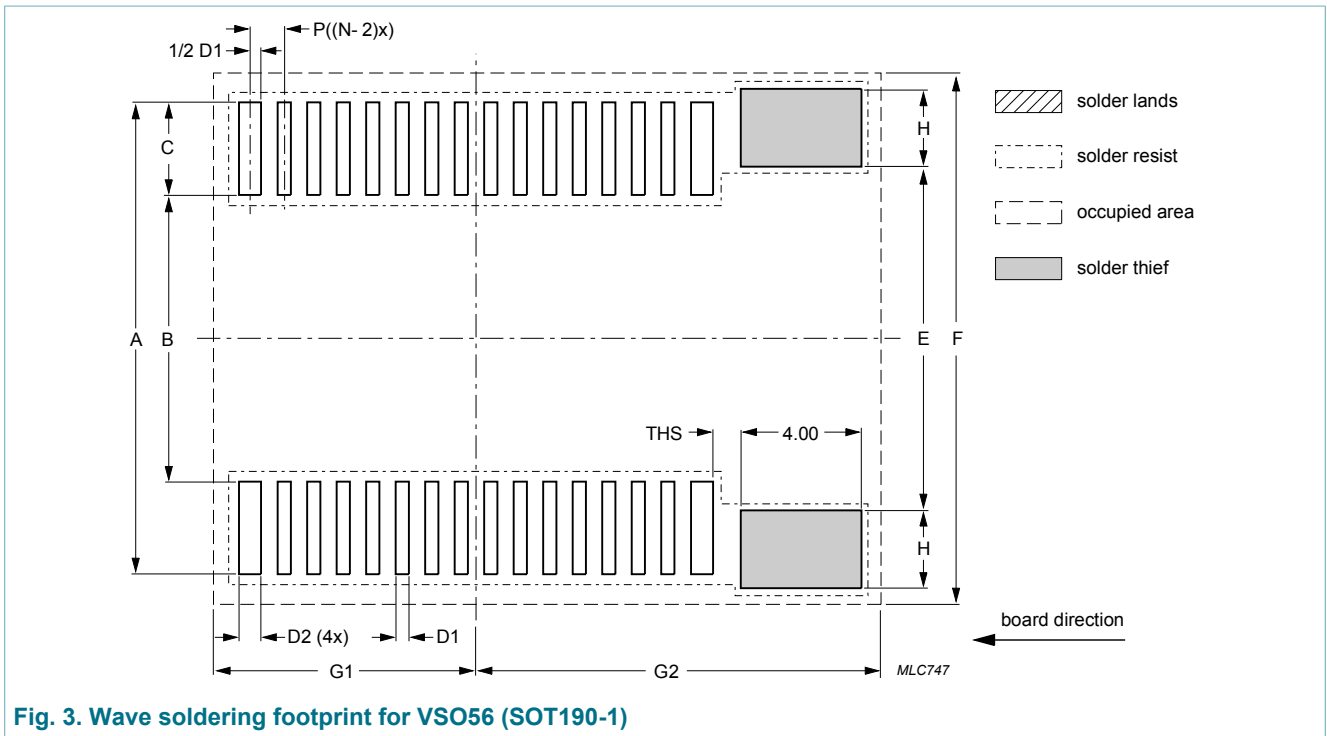


Fig. 3. Wave soldering footprint for VSO56 (SOT190-1)

4. Legal information

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